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(12) **United States Design Patent**
Celaya et al.

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(54) **SEMICONDUCTOR DEVICE PACKAGE**

(75) Inventors: **Phillip Celaya**, Gilbert, AZ (US);
Darrell D. Truhitte, Phoenix, AZ (US);
Michael J. Seddon, Gilbert, AZ (US)

(73) Assignee: **Semiconductor Components Industries, LLC**, Phoenix, AZ (US)

(**) Term: **14 Years**

(21) Appl. No.: **29/211,046**

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(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; 174/52.1,
174/52.2, 52.4; 257/666, 669, 675, 676,
678, 690, 692, 696, 697, 730, 787; 361/773,
820; 438/64, 65

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Primary Examiner—Stella Reid
Assistant Examiner—Selina Sikder

(57) **CLAIM**

We claim the ornamental design for a semiconductor device package, as shown and described.

DESCRIPTION

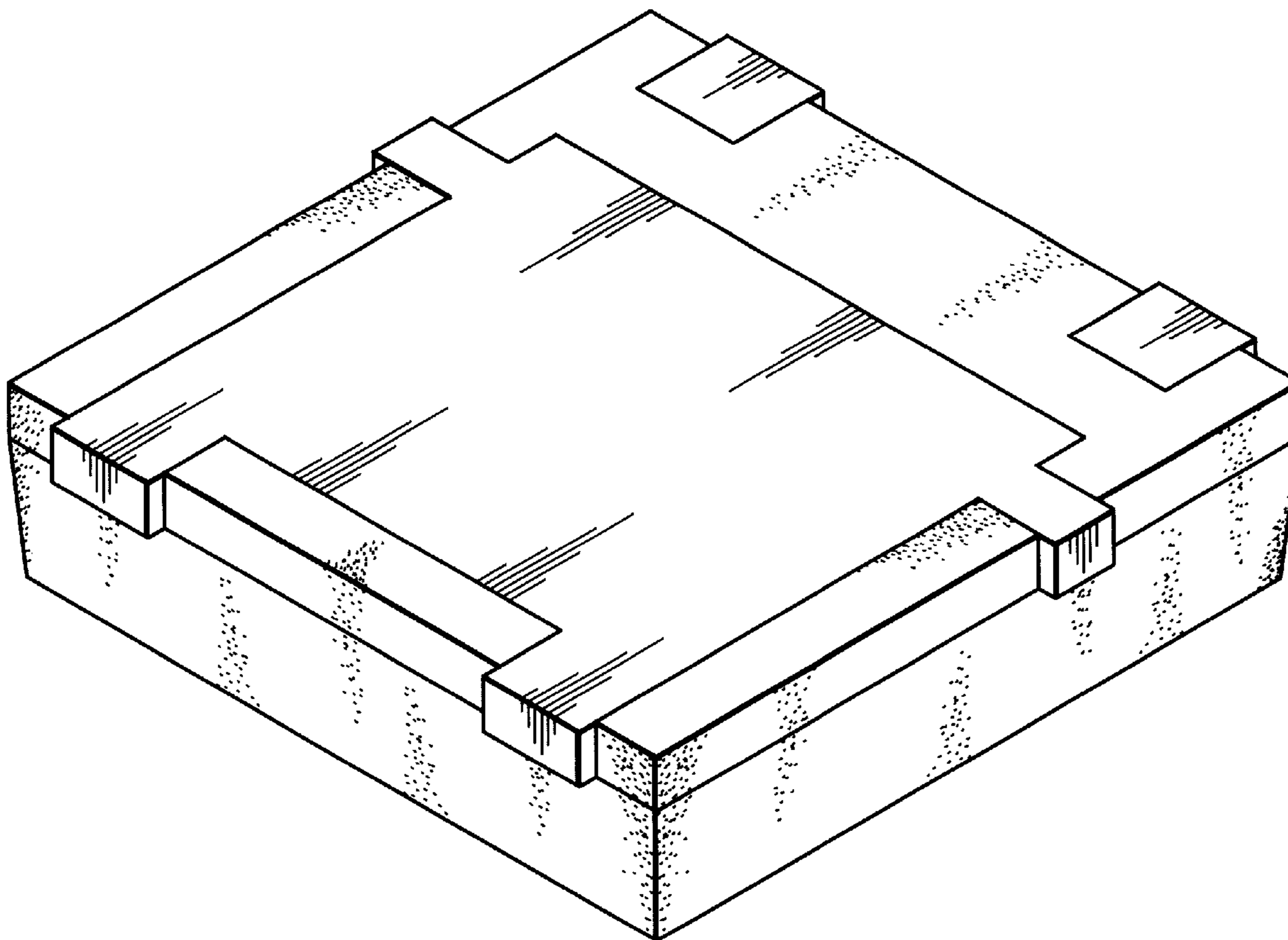
FIG. 1 is a perspective view from the front left side and below the semiconductor device package showing our new design.

FIG. 2 is a top plan view thereof;

FIG. 3 is a bottom plan view thereof; and,

FIG. 4 is an elevational view from the front side thereof.

1 Claim, 3 Drawing Sheets



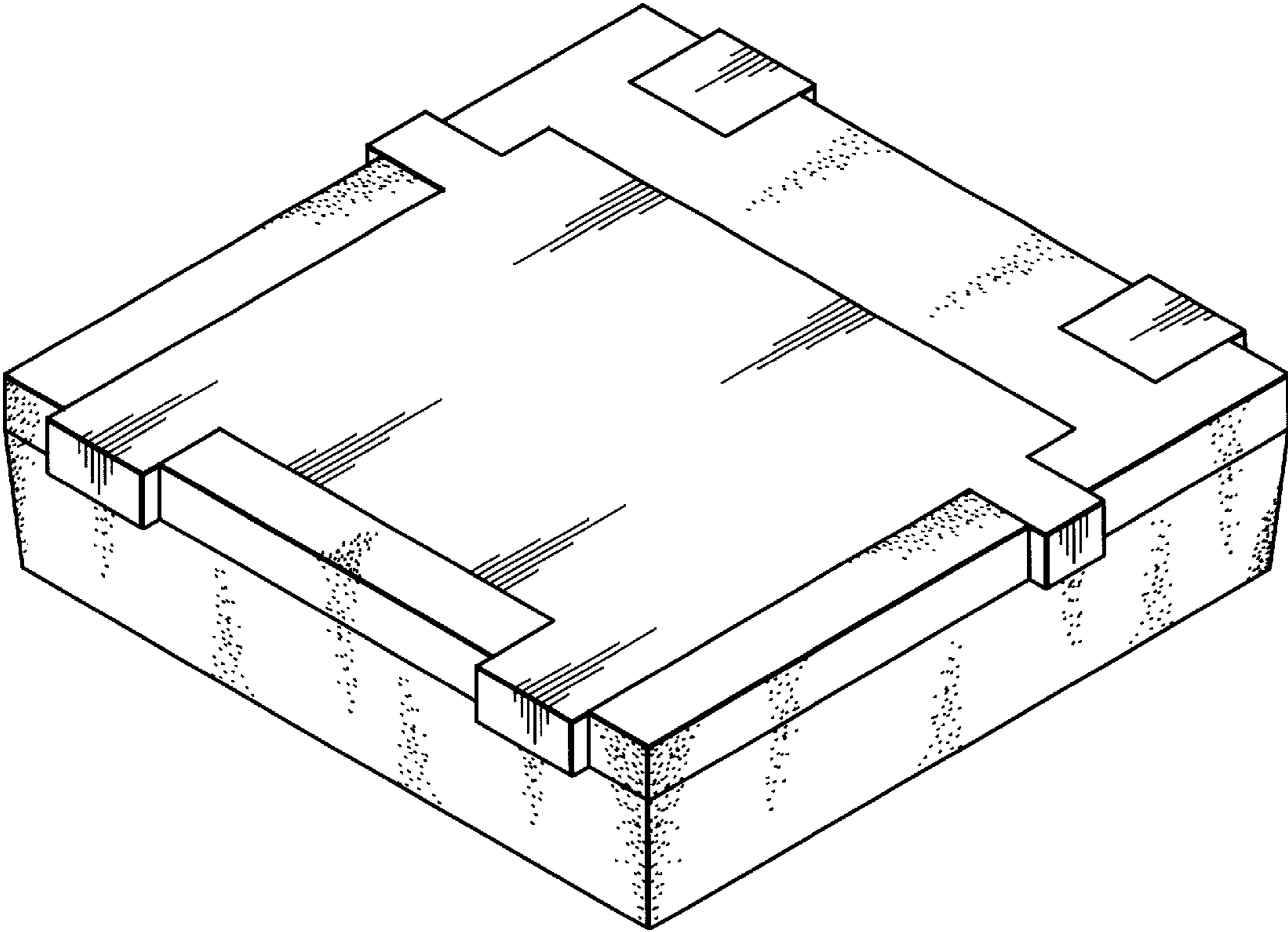


FIG. 1

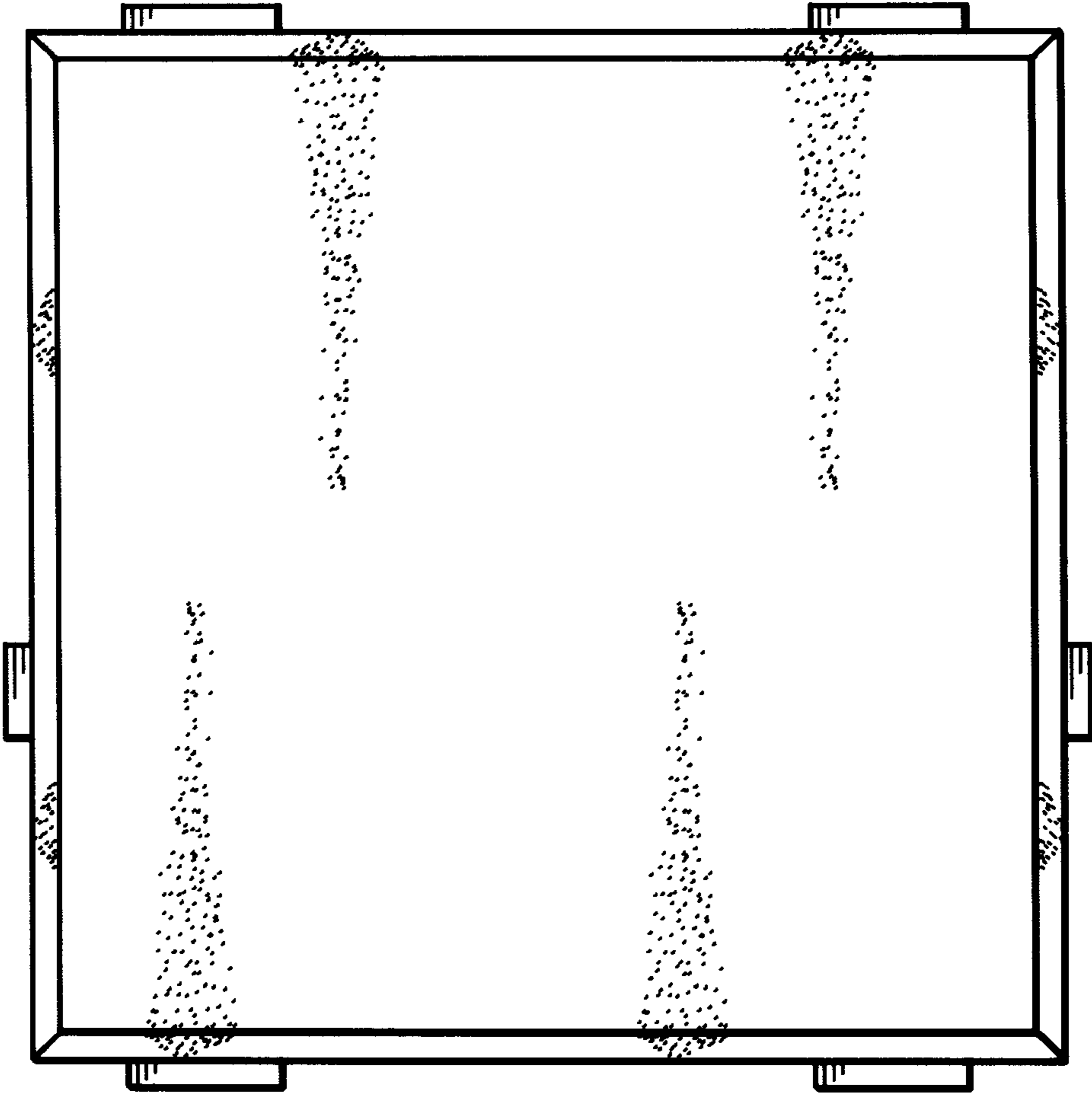


FIG. 2

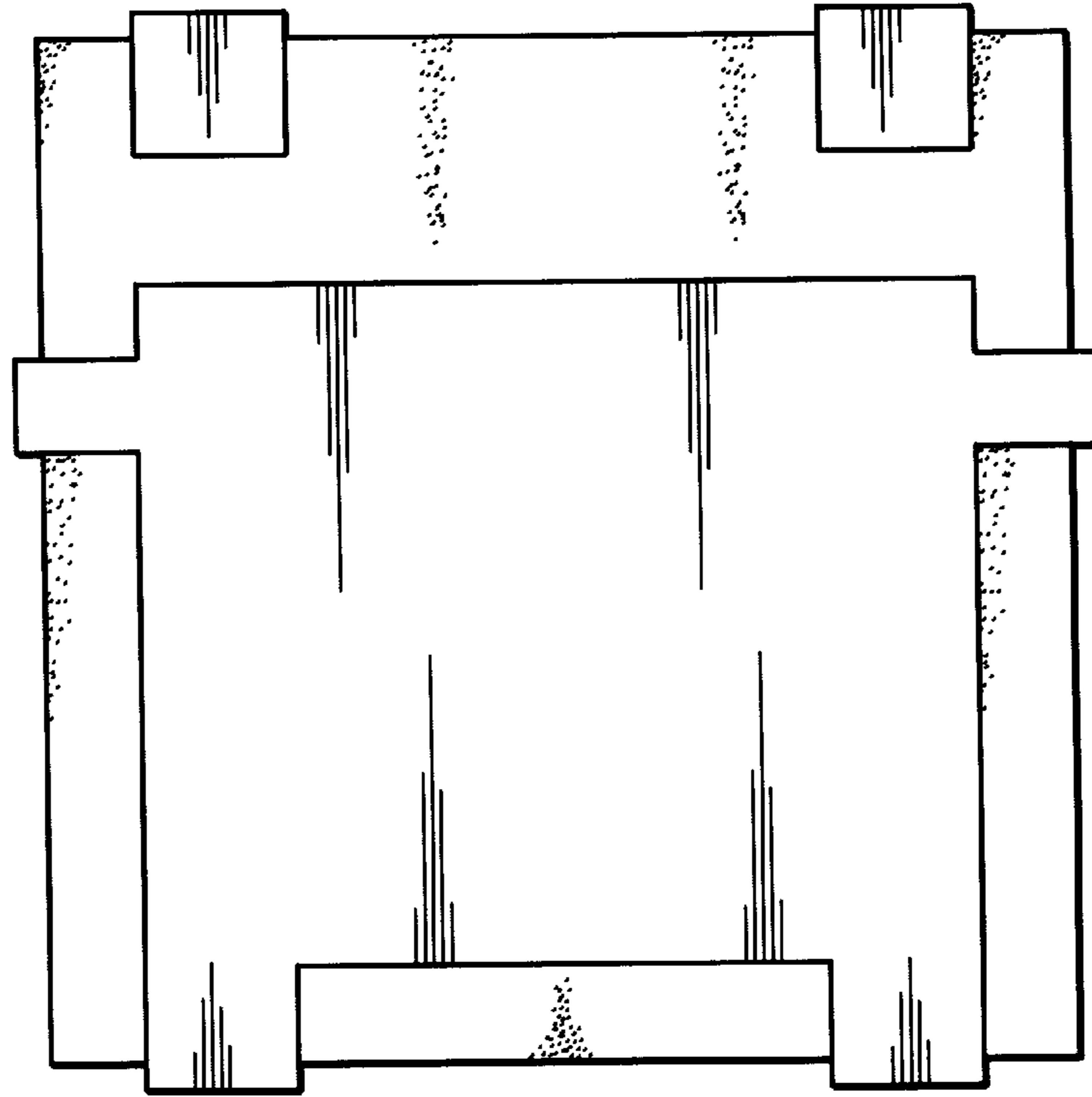


FIG. 3

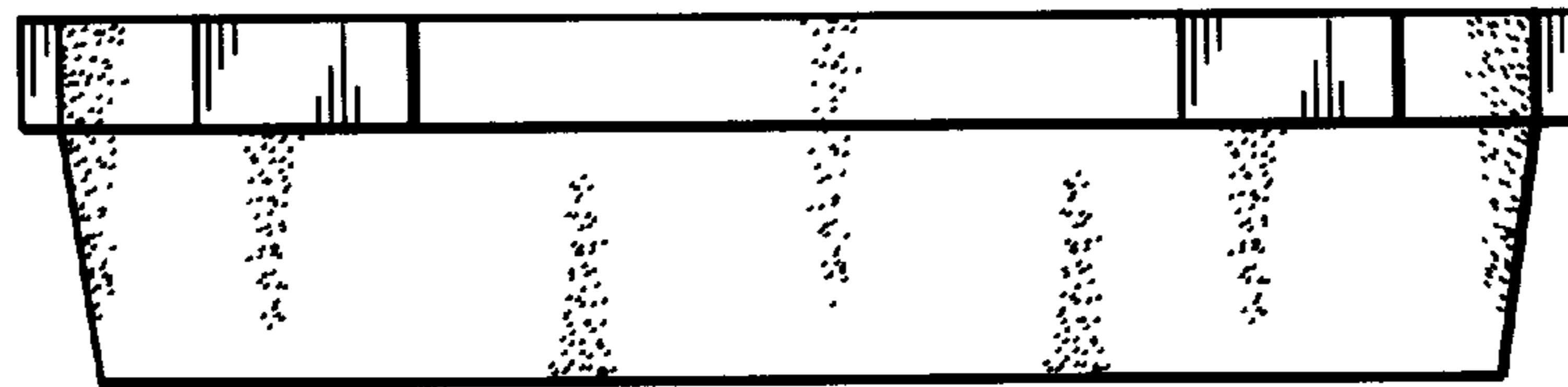


FIG. 4